

# CMSE 2008 PROGRAM

Tuesday, February 12, 2008

<b>Welcome and Introduction</b>	8:25 - 8:30am
<b>Keynote 1: Key Issues Facing Military Electronics &amp; Components</b>	8:30 - 9:15am
Murray Slovick, Editorial Director Hearst Products .....	3
<b>Session 1: Design Implementation with COTS</b>	9:15am - 12:00pm
Chairman: John Prymak, Kemet Electronics	
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1.5 <i>Noise Damping Techniques for Solid-State Storage in Military-Embedded Systems;</i> G. Drosell, SiliconSystems Inc.....	65
<b>Buffet Lunch in the Exhibition Area</b>	12:00 - 2:00pm
<b>Session 2: Packaging &amp; Soldering Impact on Components</b>	2:00 - 3:30pm
Chairman: Richard Wavrik, Sandia National Labs	
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**Exhibits and Get Acquainted Reception with Refreshment** 5:30 - 7:00pm

**Wednesday, February 13**

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<b>Session 4:</b>	<b>Components Selection &amp; Application</b>	9:00 - 12:00am
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**Buffet Lunch in the Exhibition Area** 12:00 - 2:00pm

**Session 5: Design and Process Improvements** (parallel with 6)

Chairman: Lori Bechtold, Boeing

2:00 - 5:00pm

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**Session 6: Space and Radiation Hardness** (parallel with 5)

2:00 - 5:00pm

Chairman: Larry Harzstark, Aerospace Corp.

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7.4 *Reliability Predictions;*  
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7.6 *Generalized Approach to Availability Prediction for Non Electronic Components;*  
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**Lunch** ..... 12:00 - 1:00pm

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